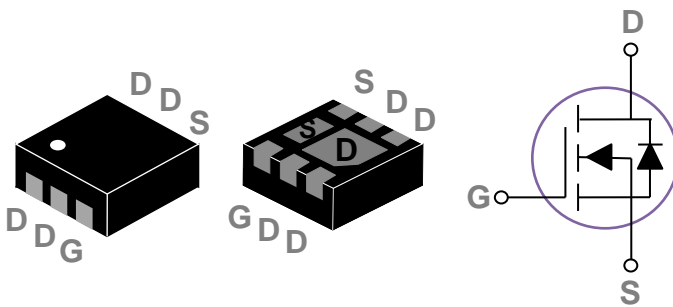


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN2x2-6L 2EP Pin Configuration



| | | |
|-------|-------|----|
| BVDSS | RDSON | ID |
| 30V | 19mΩ | 8A |

Features

- 30V,8A, $R_{DS(ON)} = 19m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|---|------------|-------|
| V_{DS} | Drain-Source Voltage | 30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| I_D | Drain Current – Continuous ($T_A=25^\circ C$) | 8 | A |
| | Drain Current – Continuous ($T_A=70^\circ C$) | 6.4 | A |
| I_{DM} | Drain Current – Pulsed ¹ | 32 | A |
| P_D | Power Dissipation ($T_A=25^\circ C$) | 2 | W |
| | Power Dissipation – Derate above 25°C | 16.1 | mW/°C |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 62 | °C/W |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|--|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 30 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =1mA | --- | 0.04 | --- | V/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =30V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =24V, V _{GS} =0V, T _J =125°C | --- | --- | 10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |

On Characteristics

| | | | | | | |
|----------------------|--|--|-----|------|-----|-------|
| R _{DS(ON)} | Static Drain-Source On-Resistance ³ | V _{GS} =10V, I _D =4A | --- | 15.5 | 19 | mΩ |
| | | V _{GS} =4.5V, I _D =3A | --- | 20.5 | 27 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.2 | 1.6 | 2.5 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -4 | --- | mV/°C |
| g _{fs} | Forward Transconductance | V _{DS} =10V, I _D =2A | --- | 4 | --- | S |

Dynamic and switching Characteristics

| | | | | | | |
|---------------------|-------------------------------------|--|--|------|-----|----|
| Q _g | Total Gate Charge ^{2, 3} | V _{DS} =15V, V _{GS} =10V, I _D =4A | --- | 5.2 | 7.8 | nC |
| Q _{gs} | Gate-Source Charge ^{2, 3} | | --- | 0.6 | 0.9 | |
| Q _{gd} | Gate-Drain Charge ^{2, 3} | | --- | 2 | 3 | |
| T _{d(on)} | Turn-On Delay Time ^{2, 3} | V _{DD} =15V, V _{GS} =10V, R _G =6Ω I _D =4A | --- | 2.8 | 4.2 | ns |
| T _r | Rise Time ^{2, 3} | | --- | 7.2 | 11 | |
| T _{d(off)} | Turn-Off Delay Time ^{2, 3} | | --- | 15.8 | 24 | |
| T _f | Fall Time ^{2, 3} | | --- | 4.6 | 7 | |
| C _{iss} | Input Capacitance | V _{DS} =15V, V _{GS} =0V, F=1MHz | --- | 490 | 750 | pF |
| C _{oss} | Output Capacitance | | --- | 80 | 120 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 55 | 90 | |
| R _g | Gate resistance | | V _{GS} =0V, V _{DS} =0V, f=1MHz | --- | 2.2 | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|------------------------------------|---|------|------|------|------|
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | 8 | A |
| I _{SM} | Pulsed Source Current ³ | | --- | --- | 16 | A |
| V _{SD} | Diode Forward Voltage ³ | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1 | V |
| t _{rr} | Reverse Recovery Time | V _R =30V, I _S =8A | --- | 130 | --- | ns |
| Q _{rr} | Reverse Recovery Charge | di/dt=100A/μs, T _J =25°C | --- | 200 | --- | nC |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

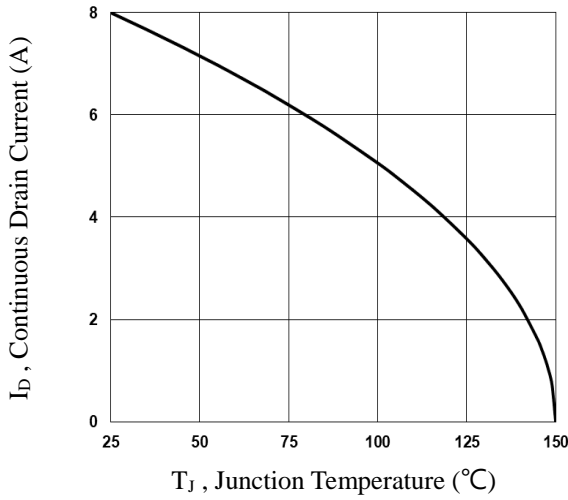


Fig.1 Continuous Drain Current vs. T_J

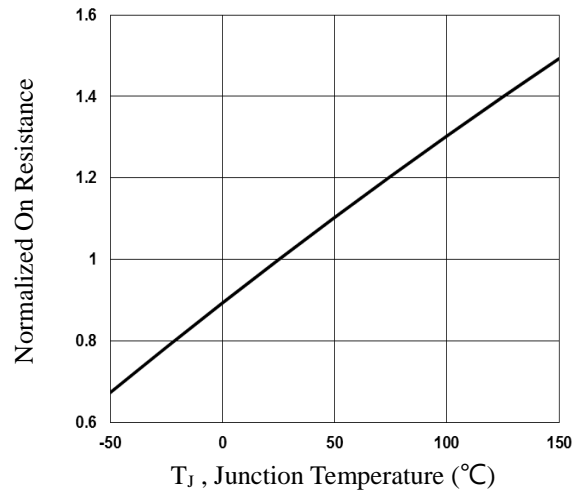


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

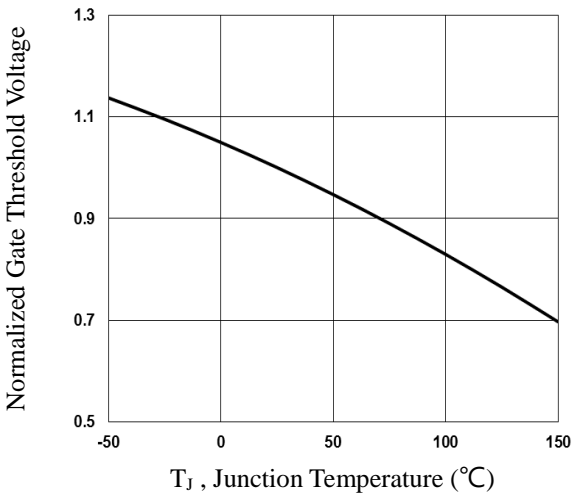


Fig.3 Normalized V_{th} vs. T_J

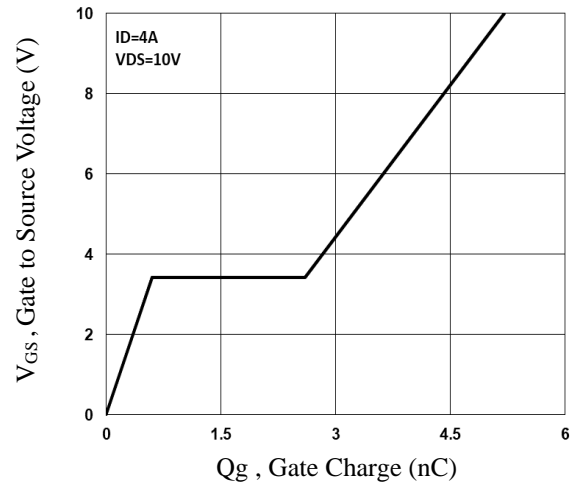


Fig.4 Gate Charge Waveform

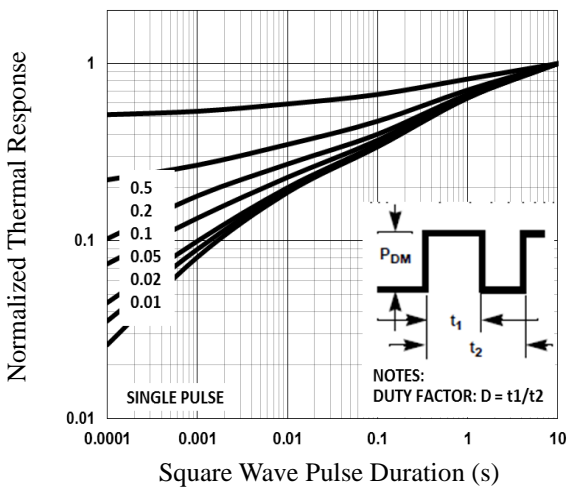


Fig.5 Normalized Transient Response

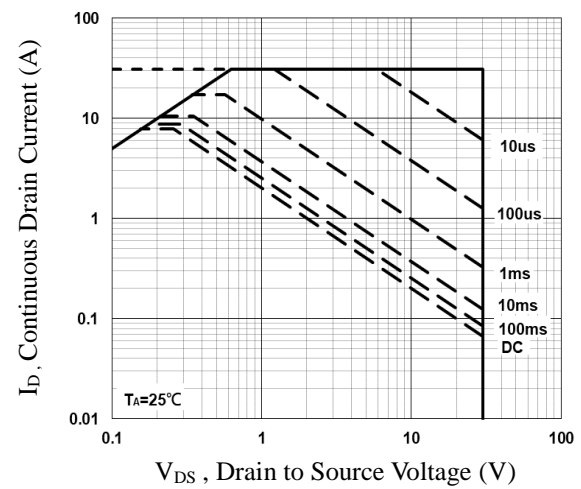


Fig.6 Maximum Safe Operation Area



Fig.7 Switching Time Waveform

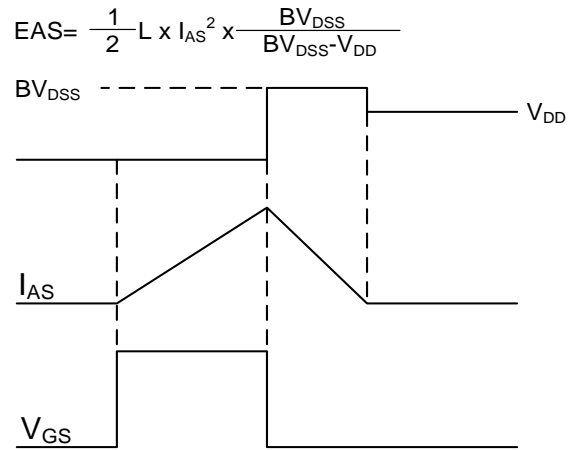
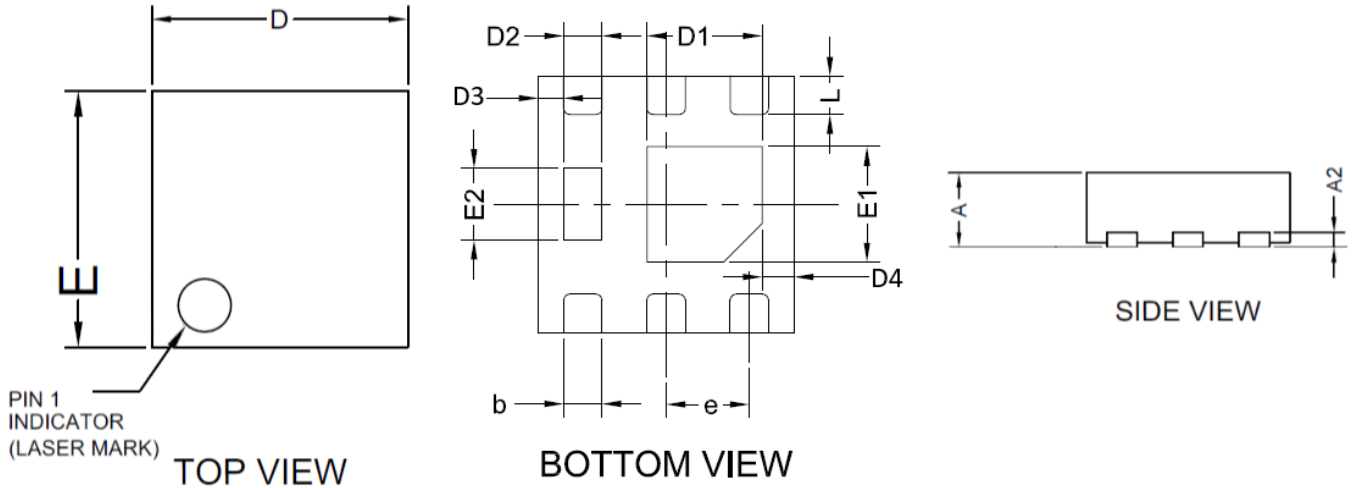


Fig.8 EAS Waveform

DFN2x2-6L 2EP PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | MAX | MIN | MAX | MIN |
| A | 0.800 | 0.500 | 0.031 | 0.019 |
| A2 | 0.250 | 0.145 | 0.010 | 0.006 |
| b | 0.350 | 0.250 | 0.014 | 0.010 |
| D | 2.100 | 1.900 | 0.083 | 0.075 |
| D1 | 1.000 | 0.800 | 0.040 | 0.031 |
| D2 | 0.350 | 0.250 | 0.014 | 0.010 |
| D3 | 0.200BSC | | 0.008BSC | |
| D4 | 0.200BSC | | 0.008BSC | |
| E | 2.100 | 1.900 | 0.083 | 0.075 |
| E1 | 1.050 | 0.800 | 0.041 | 0.031 |
| E2 | 0.66 | 0.46 | 0.026 | 0.018 |
| e | 0.650BSC | | 0.026BSC | |
| L | 0.350 | 0.250 | 0.014 | 0.010 |

RECOMMEND FOOTPRINT Information

